



A Product Line of Diodes Incorporated



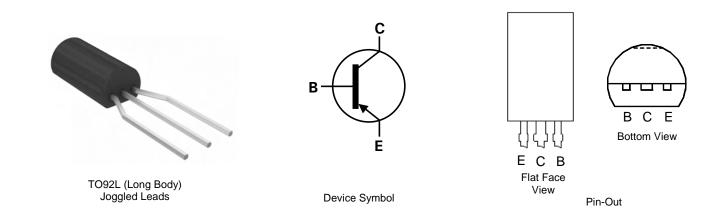
400V PNP High Voltage Transistor in TO92L

Features and Benefits

- BV_{CEO} > 400V
- Power dissipation P_D = 1W
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TO92L (Long Body)
- Case Material: molded plastic, "Green" molding compound.
- UL Flammability Classification Rating 94V-0
- Terminals: Finish Bright Tin (B)
- Weight: 0.272 grams (approximate)



Ordering Information (Note 4)

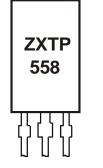
Product	Package	Marking	Leads	Quantity
ZXTP558LSTZ	TO92L	ZXTP558	Joggled	2,000 taped per Ammo Box

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl)

and <1000ppm antimony compounds. 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



ZXTP558 = Product Type Marking Code





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-400	V
Collector-Emitter Voltage	V _{CEO}	-400	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	lc	-500	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 5)	PD	1	W	
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	125	°C/W	
Thermal Resistance, Junction to Lead (Note 6)	R _{θJL}	50	°C/W	
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C	

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	≥ 8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

Notes: 5. For the through-hole device mounted vertically, in still air conditions, with the lead length 6mm from the bottom of package to the board.

6. Thermal resistance from junction to solder-point (2mm from the bottom of package along the collector lead).

7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.





Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-400	_	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	-400			V	I _C = -1mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7			V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	_		-100	nA	V _{CB} = -320V
Emitter Cutoff Current	I _{CES}	_		-100	nA	V _{CE} = -320V
Base Cutoff Current	I _{EBO}	_		-100	nA	$V_{BE} = -5V$
DC Current Gain (Note 8)	h _{FE}	100	—	_		$I_{C} = -1mA, V_{CE} = -10V$
DC Current Gain (Note 8)		100		300	_	I _C = -50mA
Collector-Emitter Saturation Voltage (Note 8)	V _{CE(sat)}	—		-0.2	V	$I_{C} = -20mA, I_{B} = -2mA$
				-0.5		$I_{C} = -50mA, I_{B} = -6mA$
Base-Emitter Turn-On Voltage	V _{BE(on)}	_		-0.9	V	$V_{CE} = -10V, I_{C} = -50mA$
Base-Emitter Saturation Voltage	V _{BE(sat)}			-0.9	V	$I_{C} = -50 \text{mA}, I_{B} = -5 \text{mA}$
Output Capacitance (Note 8)	C _{obo}	_		5	pF	$V_{CB} = -20V, f = 1.0MHz$
Current Gain-Bandwidth Product	f _T	50			MHz	$V_{CE} = -20V$, $I_C = -10mA$, f = 20MHz
Turn-On Time	t _{on}	_	95	_	ns	V _{CE} = -100V, I _C = -50mA
Turn-Off Time	t _{off}	—	1600	_	ns	$I_{B1} = 5mA, I_{B2} = -10mA$

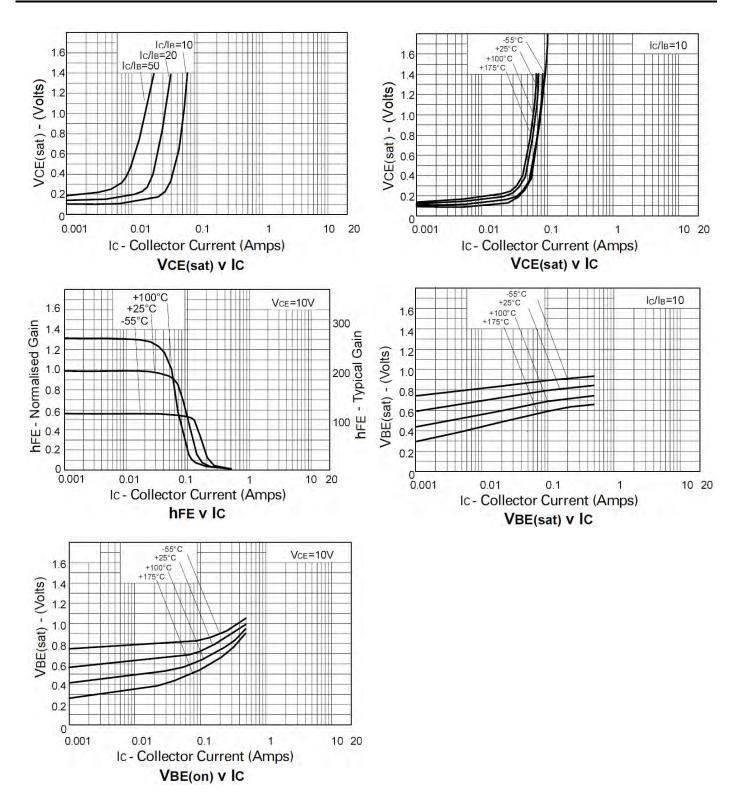
Note: 8. Measured under pulsed conditions. Pulse width \leq 300µs; Duty cycle \leq 2%.







Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)







TO92L

Min

3.70

1.28

0.35

0.60

0.35

4.70

4.00

2.30

7.80

10.10

13.80 0.00

Max

4.10

1.58

0.55

0.80

0.45

5.10

-2.70

8.20

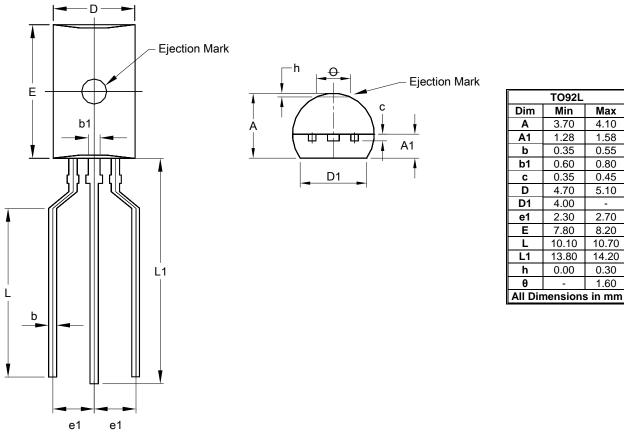
10.70

14.20

0.30

1.60

Package Outline Dimensions









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